

Amendments to the Claims:

Claims 1-3 (Canceled)

4. **(New)** A circuit board including:
 - a substrate;
 - at least one circuit pattern provided on opposite sides of said substrate;
 - an anti-soldering layer provided on said at least one circuit pattern on one side of said substrate to prevent soldering material from sticking to said at least one circuit pattern;
 - at least one silk-screen printing area provided on said anti-soldering layer to indicate where a selected electric or electronic part or device is to be mounted;
 - at least one terminal hole formed in said substrate at a center of said at least one silk-screen printing area;
 - a conductor layer formed on an inner circumference of said at least one terminal hole;
 - a substrate-exposed zone provided on said one side of said substrate, said substrate-exposed zone being free of said at least one circuit pattern, said anti-soldering layer and said at least one silk-screen printing area, such that said one side of said substrate is exposed in said substrate-exposed zone;
wherein said substrate-exposed zone is a contiguous substrate-exposed zone that extends continuously across a portion of said one side of said substrate and between portions of said at least one silk-screen printing area so as to extend across said center of said at least one silk-screen printing area where said at least one terminal hole is formed.
5. **(New)** A circuit board according to claim 4, wherein
said conductor layer formed on said inner circumference of said at least one terminal hole is contiguous to said at least one circuit pattern.

6. (New) A soldering structure for soldering a selected electric or electronic part or device having at least one terminal lead on a circuit board, including:

- a substrate;
- at least one circuit pattern provided on opposite sides of said substrate;
- an anti-soldering layer provided on said at least one circuit pattern on one side of said substrate to prevent soldering material from sticking to said at least one circuit pattern;
- at least one silk-screen printing area provided on said anti-soldering layer to indicate where the selected electric or electronic part or device is to be mounted;
- at least one terminal hole formed in said substrate at a center of said at least one silk-screen printing area;
- a conductor layer formed on an inner circumference of said at least one terminal hole;
- a substrate-exposed zone provided on said one side of said substrate, said substrate-exposed zone being free of said at least one circuit pattern, said anti-soldering layer and said at least one silk-screen printing area, such that said one side of said substrate is exposed in said substrate-exposed zone;
- wherein said substrate-exposed zone is a contiguous substrate-exposed zone that extends continuously across a portion of said one side of said substrate and between portions of said at least one silk-screen printing area so as to extend across said center of said at least one silk-screen printing area where said at least one terminal hole is formed,
- such that, when the selected electric or electronic part or device is mounted on the at least one silk-screen printing area on said one side of said substrate with the at least one terminal lead passing through said at least one terminal hole, a space is formed between said exposed substrate surface of said substrate in said substrate-exposed zone and a bottom of the selected electric or electronic part or device, and at least one annular space respectively defined between the at least one terminal lead and the conductor layer is filled with soldering material.